

Silicon Switching Diode

- For high-speed switching applications

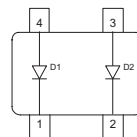
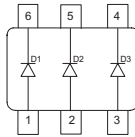
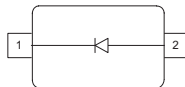
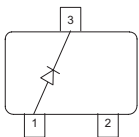


BAS16
BAS16W

BAS16-02L
BAS16-02V
BAS16-02W
BAS16-03W

BAS16S
BAS16U

BAS16-07L4



Type	Package	Configuration	Marking
BAS16	SOT23	single	A6s
BAS16-02L*	TSLP-2-1	single, leadless	A6
BAS16-02V	SC79	single	6
BAS16-02W	SCD80	single	A6
BAS16-03W	SOD323	single	B
BAS16-07L4*	TSLP-4-4	parallel pair, leadless	6A
BAS16S	SOT363	parallel triple	A6s
BAS16U	SC74	parallel triple	A6s
BAS16W	SOT323	single	A6s

* Preliminary Data

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	80	V
Peak reverse voltage	V_{RM}	85	
Forward current	I_F		mA
BAS16		250	
BAS16-02L, -07L4		200	
BAS16-02V, -02W		200	
BAS16-03W		250	
BAS16S		200	
BAS16U		200	
BAS16W		250	
Non-repetitive peak surge forward current	I_{FSM}		A
$t = 1 \mu\text{s}$, BAS16/ S/ U/ W/ -03W		4.5	
$t = 1 \mu\text{s}$, BAS16-02L/ -02V/ -02W/ -07L4		2.5	
$t = 1 \text{s}$		0.5	
Total power dissipation	P_{tot}		mW
BAS16, $T_S \leq 54^\circ\text{C}$		370	
BAS16-02L, -07L4, $T_S \leq 130^\circ\text{C}$		250	
BAS16-02V, -02W, $T_S \leq 120^\circ\text{C}$		250	
BAS16-03W, $T_S \leq 116^\circ\text{C}$		250	
BAS16S, $T_S \leq 85^\circ\text{C}$		250	
BAS16U, $T_S \leq 113^\circ\text{C}$		250	
BAS16W, $T_S \leq 119^\circ\text{C}$		250	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BAS16, BAS16S		≤ 260	
BAS16-02L, -07L4		≤ 80	
BAS16-02V, -02W		≤ 120	
BAS16-03W		≤ 135	
BAS16U		≤ 150	
BAS16W		≤ 125	

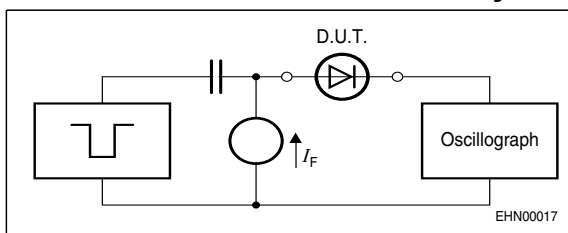
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)} = 100 \mu A$	$V_{(BR)}$	85	-	-	V
Reverse current $V_R = 75 V$ $V_R = 25 V, T_A = 150 \text{ }^{\circ}C$ $V_R = 75 V, T_A = 150 \text{ }^{\circ}C$	I_R	- - -	- - -	0.1 30 50	μA
Forward voltage $I_F = 1 mA$ $I_F = 10 mA$ $I_F = 50 mA$ $I_F = 100 mA$ $I_F = 150 mA$	V_F	- - - - -	- - - - -	715 855 1000 1200 1250	mV
Forward recovery voltage $I_F = 10 mA, t_P = 20 ns$	V_{fr}	-	-	1.75	V

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Diode capacitance $V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_T	-	-	2	pF
Reverse recovery time $I_F = 10\text{ mA}$, $I_R = 10\text{ mA}$, measured at $I_R = 1\text{ mA}$, $R_L = 100\text{ }\Omega$	t_{rr}	-	-	4	ns

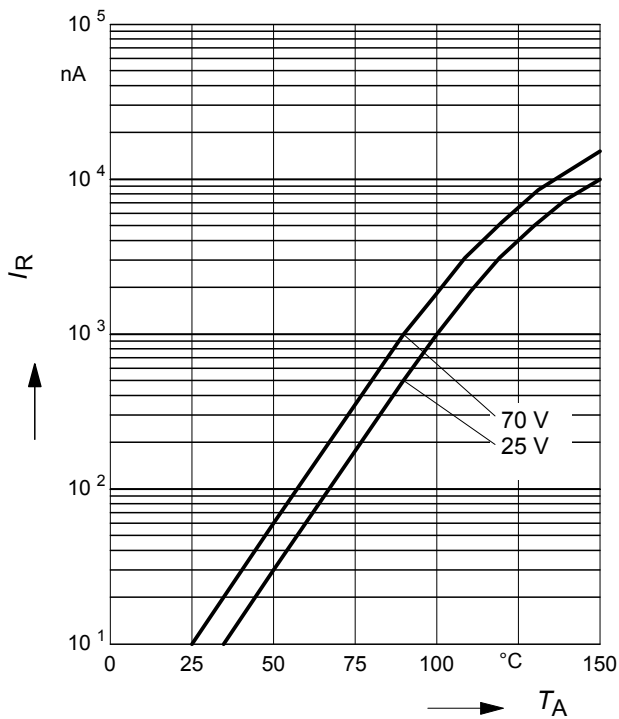
Test circuit for reverse recovery time


Pulse generator: $t_p = 100\text{ ns}$, $D = 0.05$, $t_r = 0.6\text{ ns}$,
 $R_i = 50\ \Omega$

Oscilloscope: $R = 50\ \Omega$, $t_r = 0.35\text{ ns}$, $C = 0.05\text{ pF}$

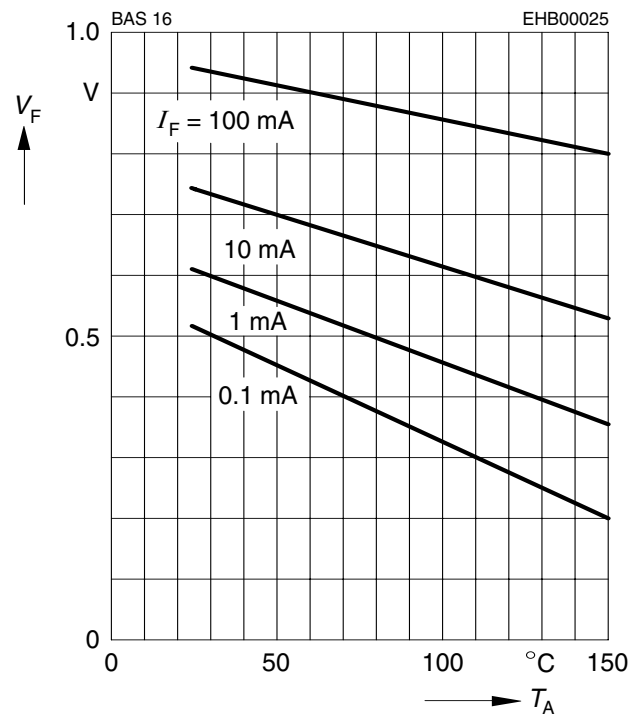
Reverse current $I_R = f(T_A)$

V_R = Parameter



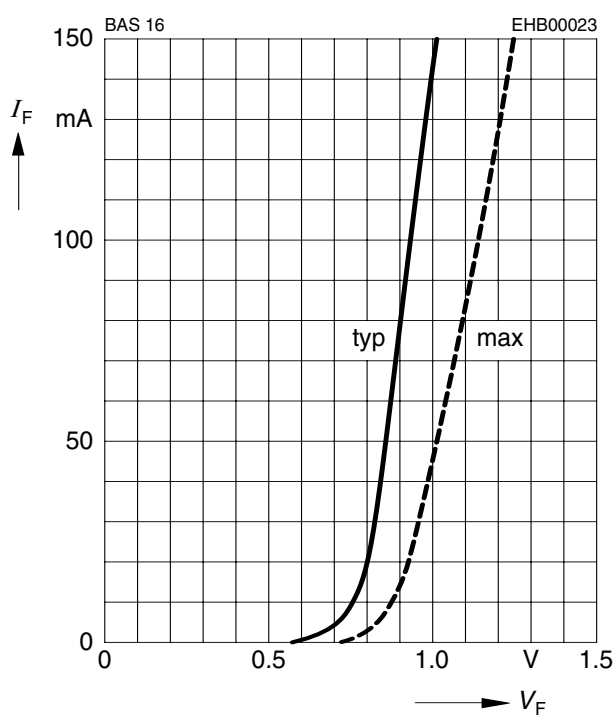
Forward Voltage $V_F = f(T_A)$

I_F = Parameter



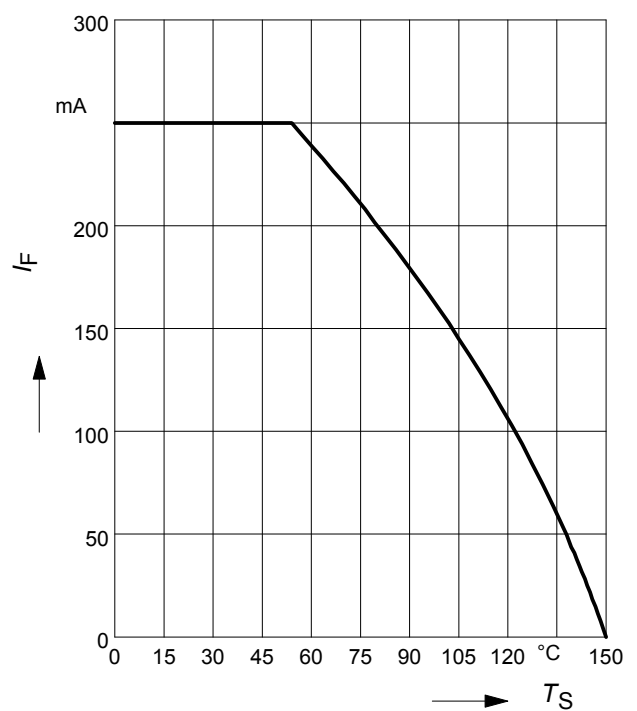
Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



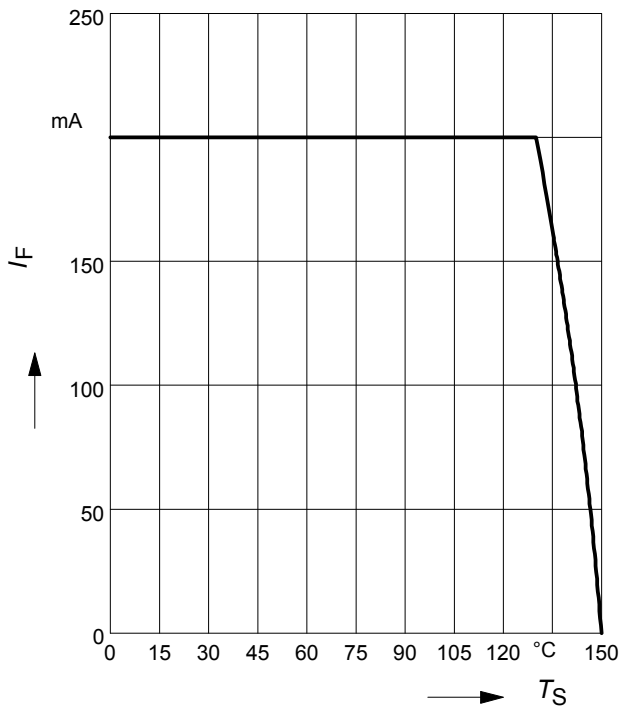
Forward current $I_F = f(T_S)$

BAS16



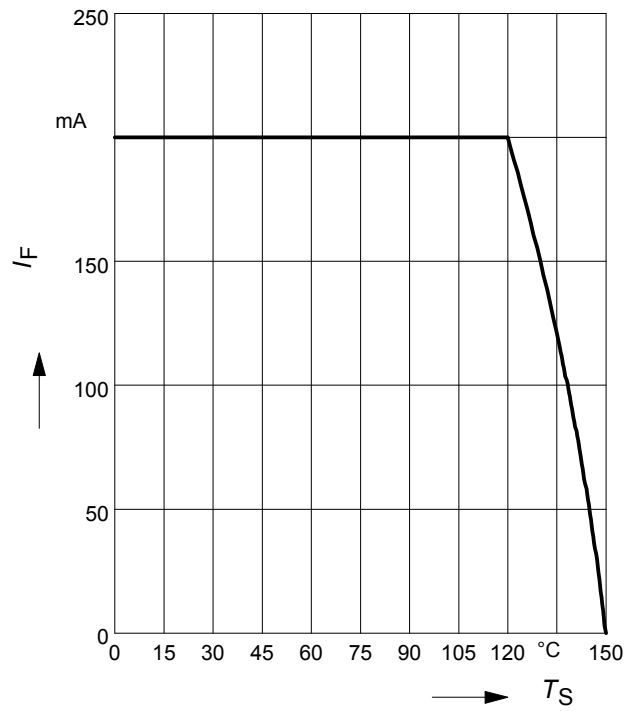
Forward current $I_F = f(T_S)$

BAS16-02L, -07L4



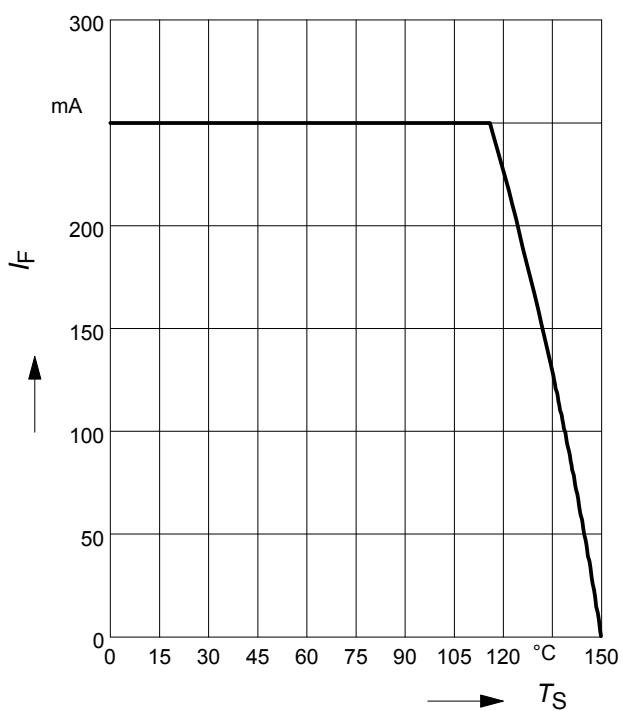
Forward current $I_F = f(T_S)$

BAS16-02V, -02W



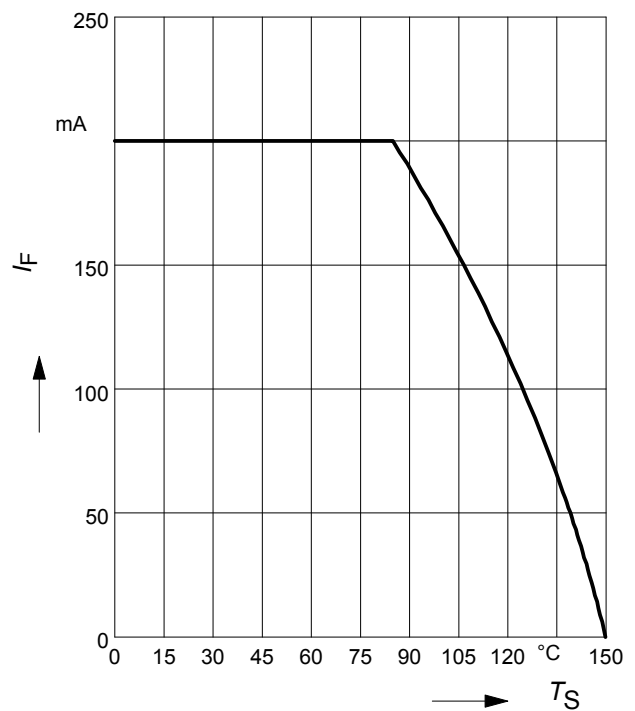
Forward current $I_F = f(T_S)$

BAS16-03W



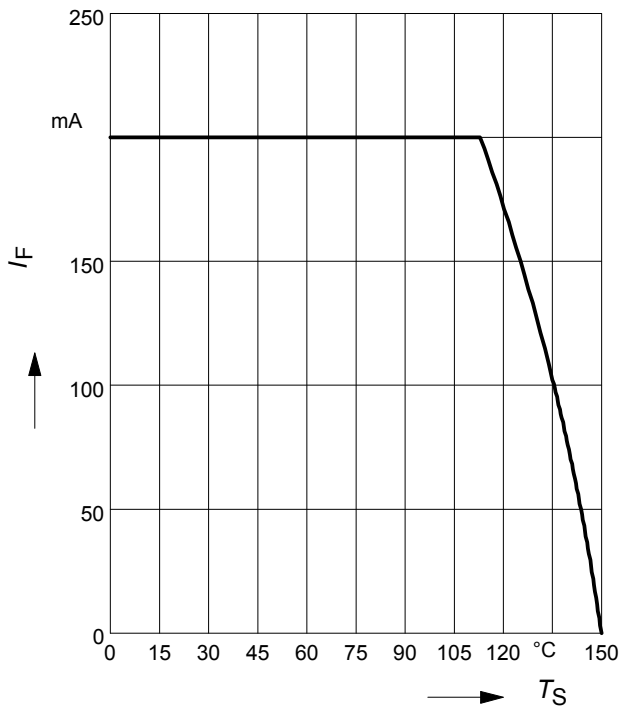
Forward current $I_F = f(T_S)$

BAS16S



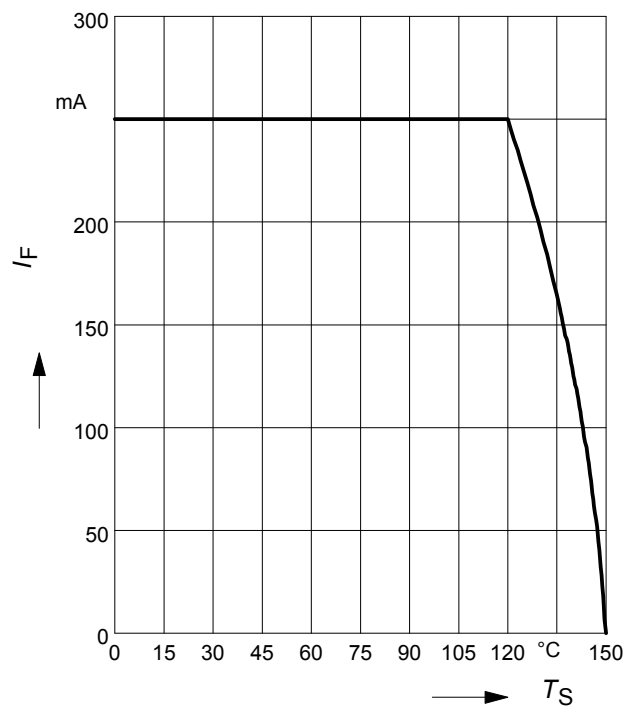
Forward current $I_F = f(T_S)$

BAS16U



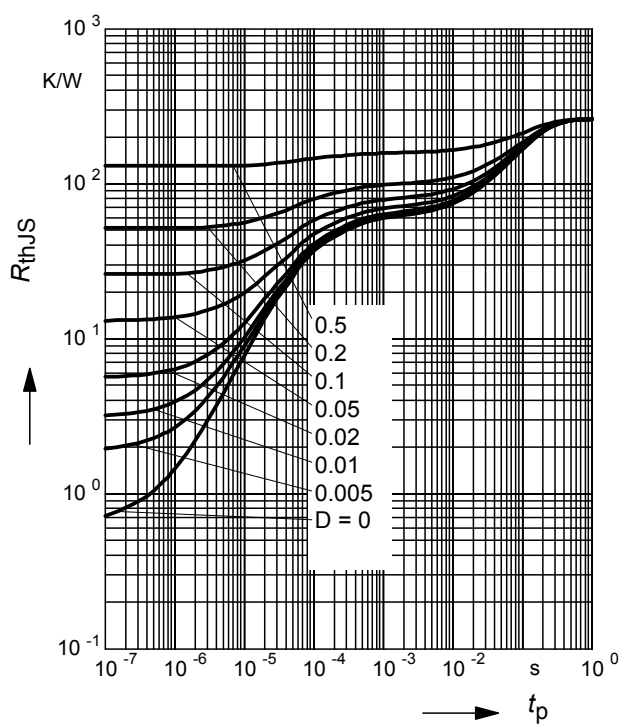
Forward current $I_F = f(T_S)$

BAS16W



Permissible Puls Load $R_{thJS} = f(t_p)$

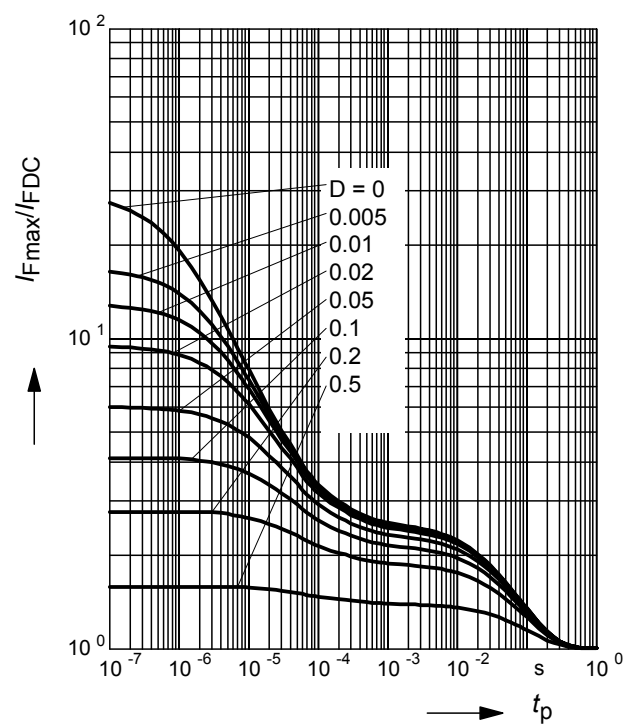
BAS16



Permissible Pulse Load

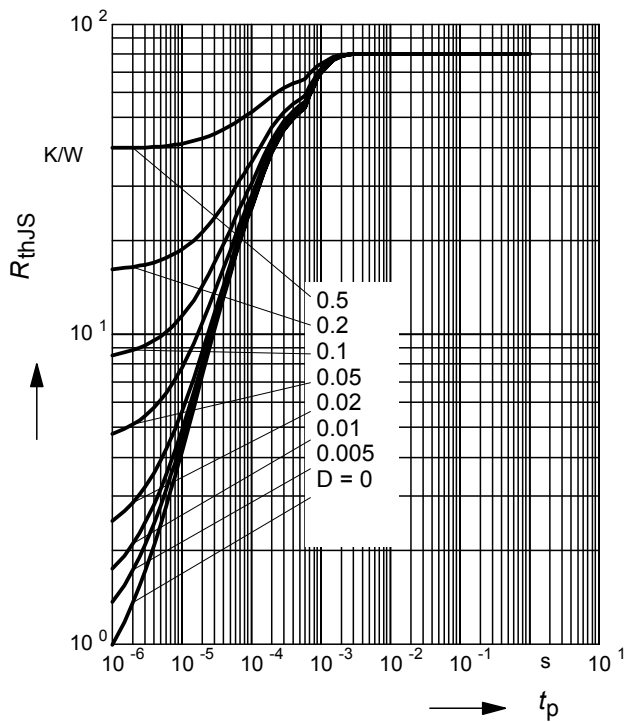
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS16



Permissible Puls Load $R_{thJS} = f(t_p)$

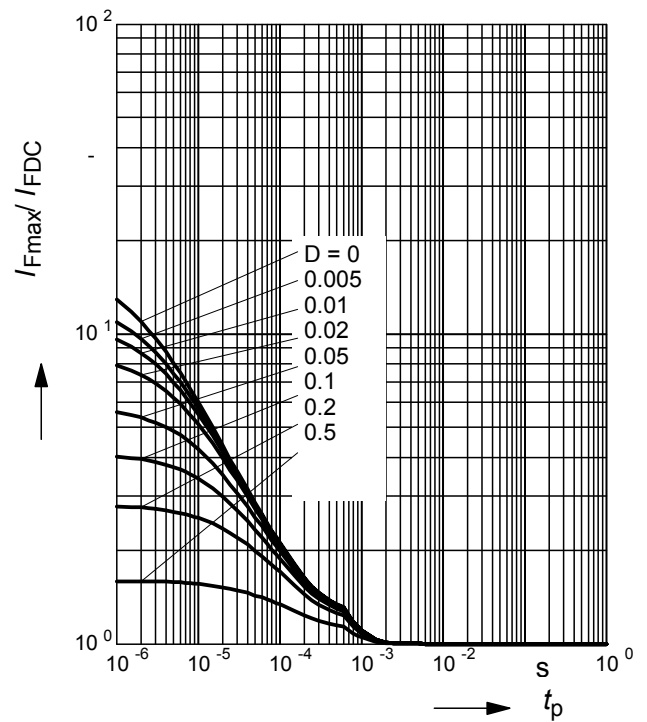
BAS16-02L, -07L4



Permissible Pulse Load

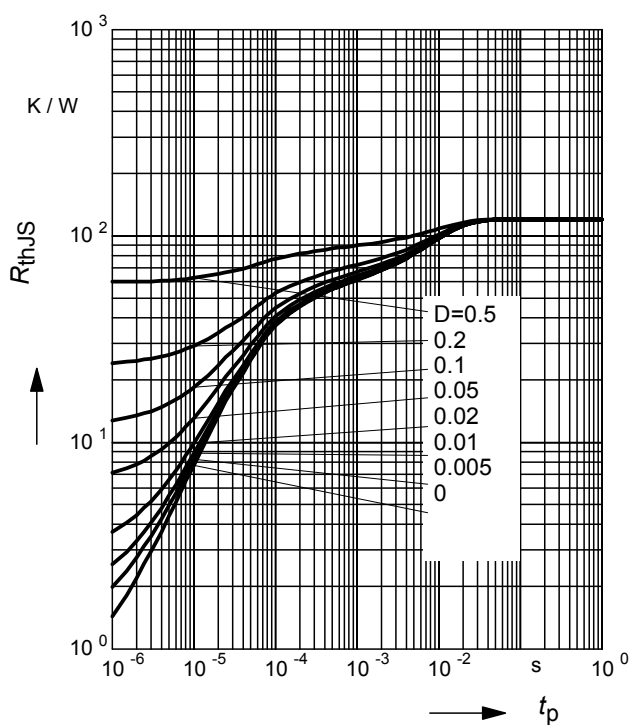
$I_{Fmax}/I_{FDC} = f(t_p)$

BAS16-02L, -07L4



Permissible Puls Load $R_{thJS} = f(t_p)$

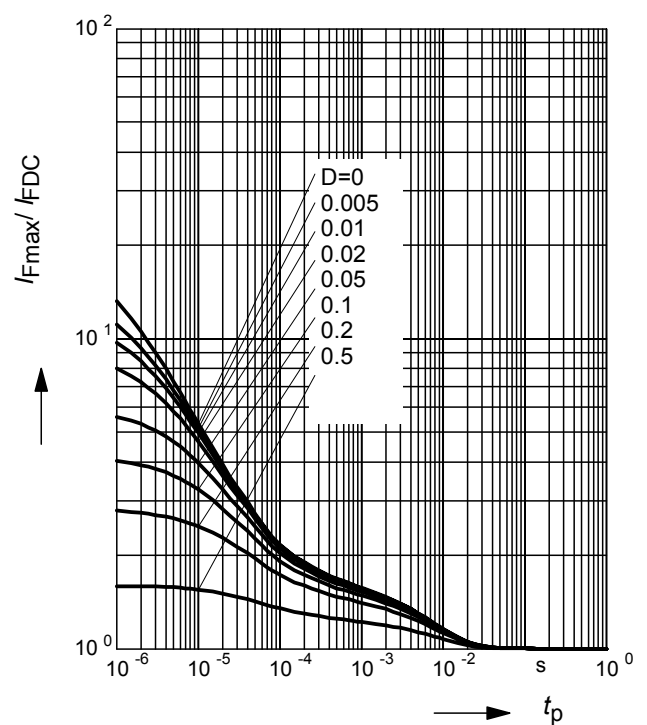
BAS16-02V, -02W



Permissible Pulse Load

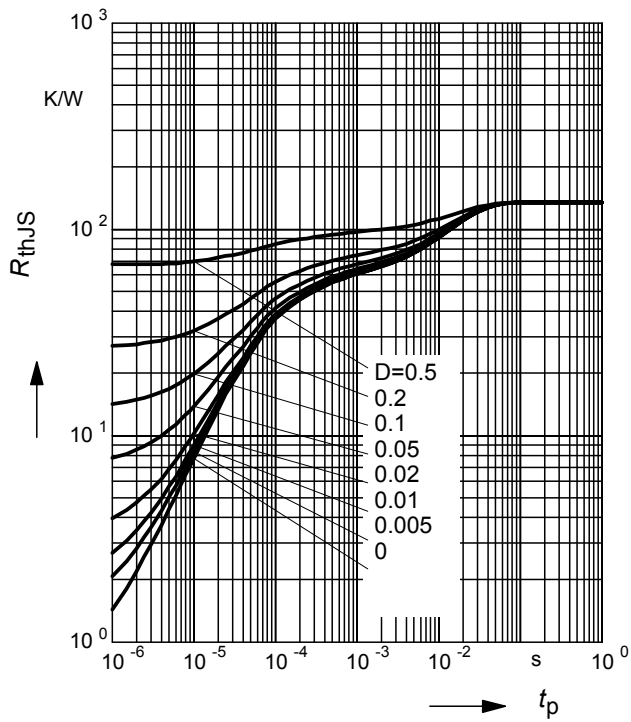
$I_{Fmax}/I_{FDC} = f(t_p)$

BAS16-02V, -02W



Permissible Puls Load $R_{thJS} = f(t_p)$

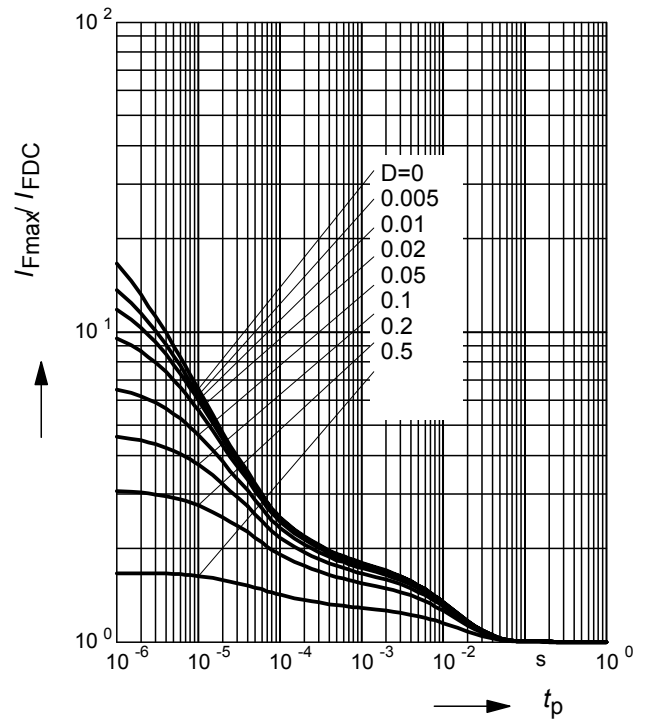
BAS16-03W



Permissible Pulse Load

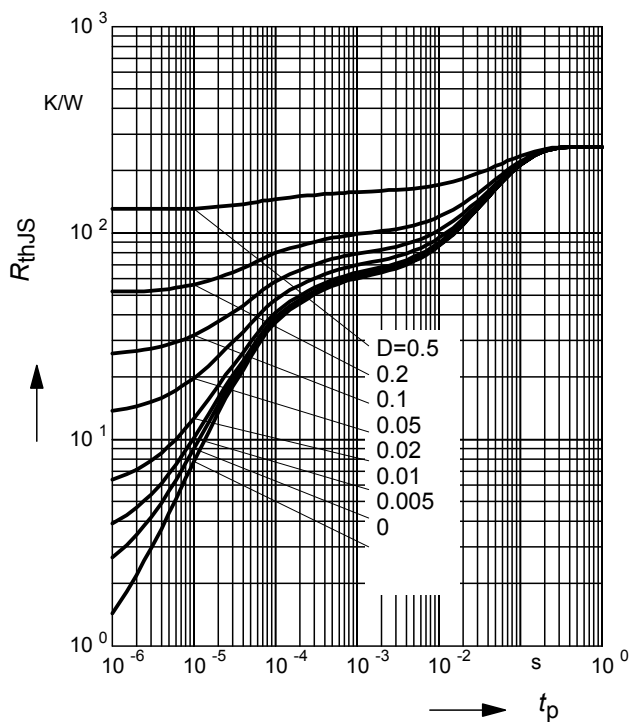
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS16-03W



Permissible Puls Load $R_{thJS} = f(t_p)$

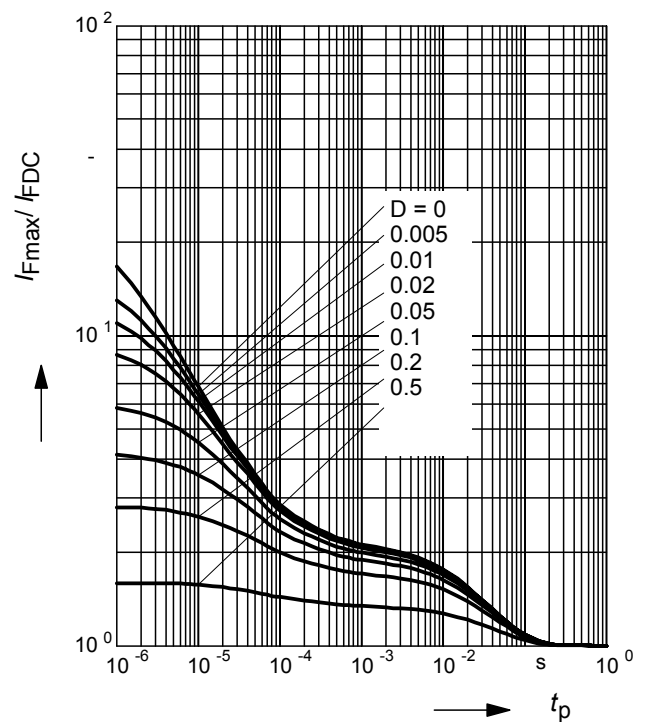
BAS16S



Permissible Pulse Load

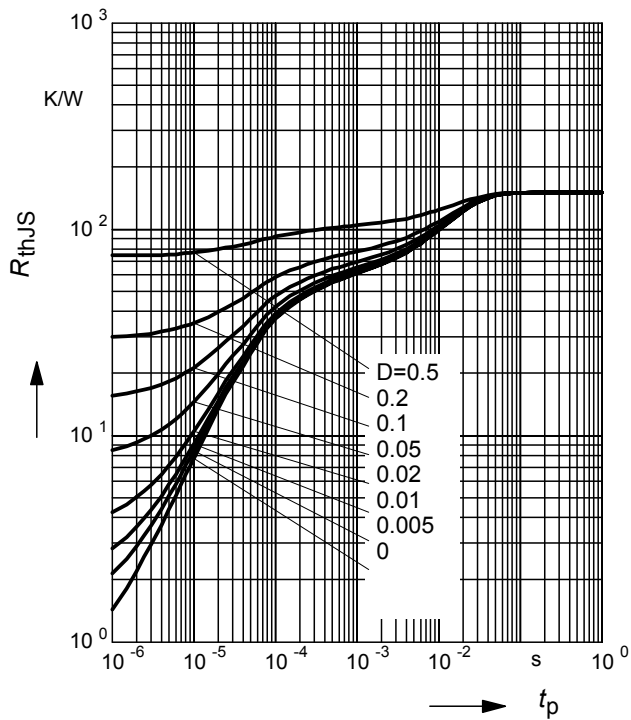
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS16S



Permissible Puls Load $R_{thJS} = f(t_p)$

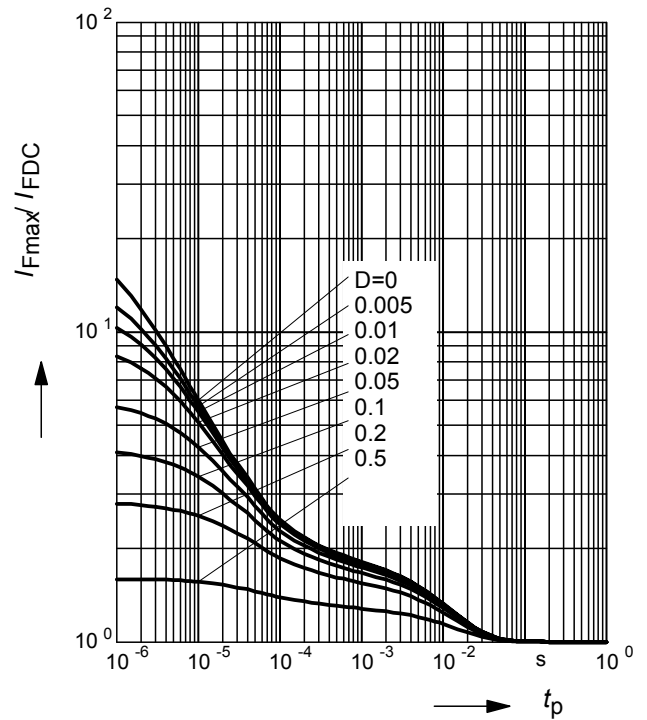
BAS16U



Permissible Pulse Load

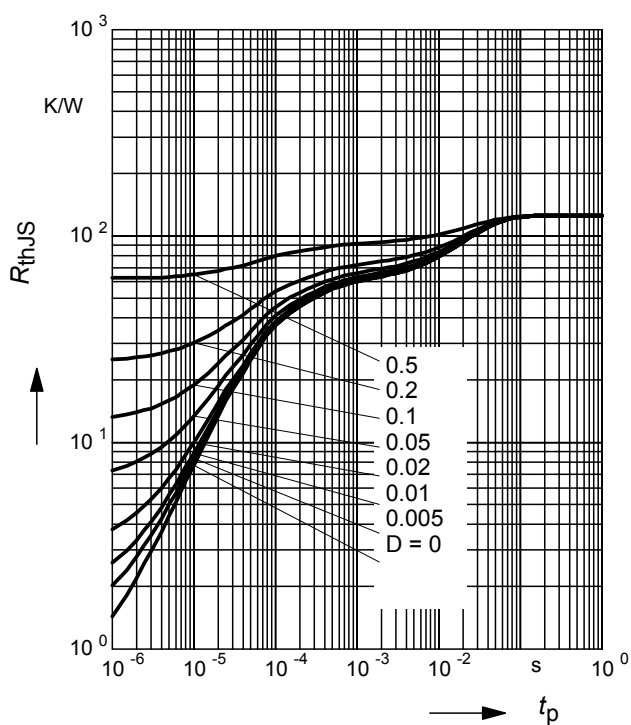
$I_{Fmax}/I_{FDC} = f(t_p)$

BAS16U



Permissible Puls Load $R_{thJS} = f(t_p)$

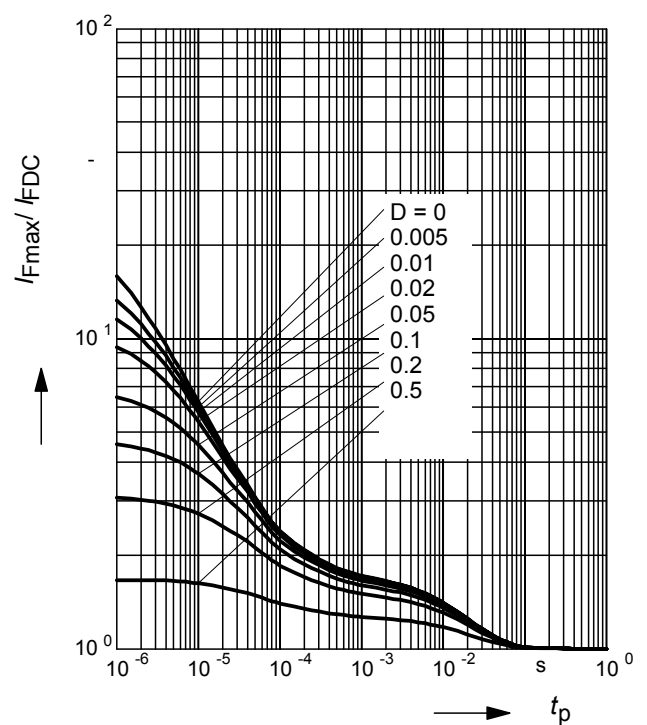
BAS16W



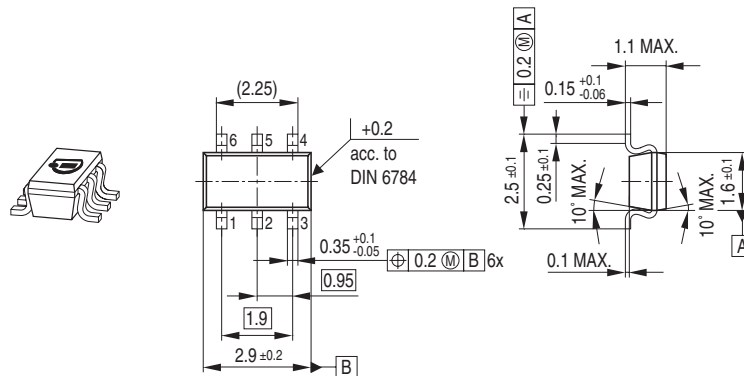
Permissible Pulse Load

$I_{Fmax}/I_{FDC} = f(t_p)$

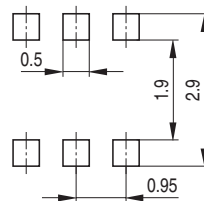
BAS16W



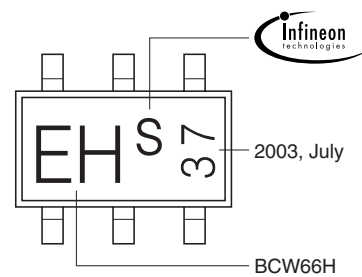
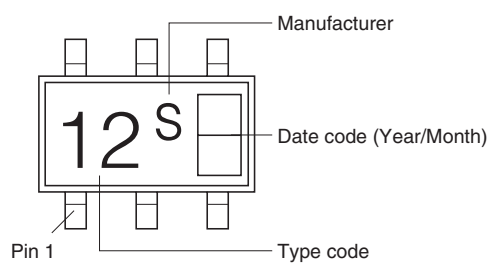
Package Outline



Foot Print



Marking Layout

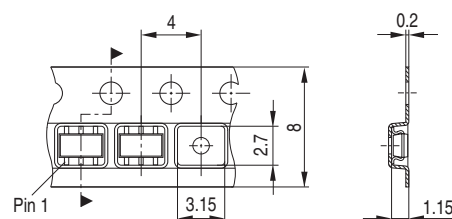


Example

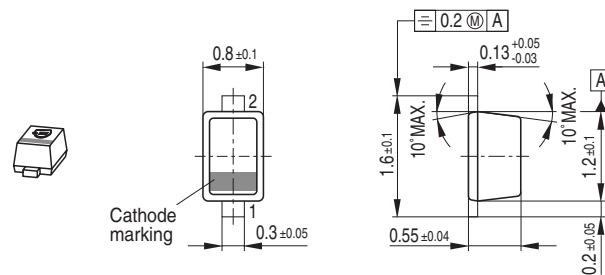
Packing

Code E6327: Reel ø180 mm = 3.000 Pieces/Reel

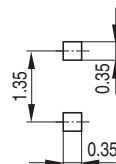
Code E6433: Reel ø330 mm = 10.000 Pieces/Reel



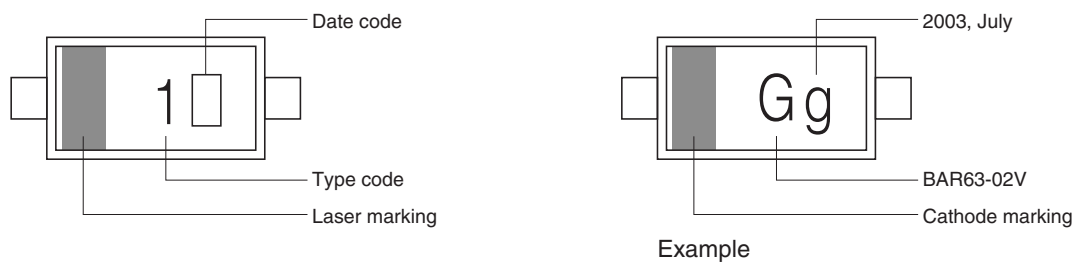
Package Outline



Foot Print



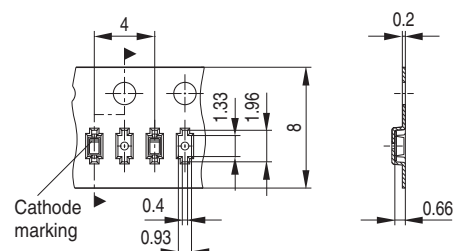
Marking Layout



Packing

Code E6327: Reel $\varnothing 180$ mm = 3.000 Pieces/Reel

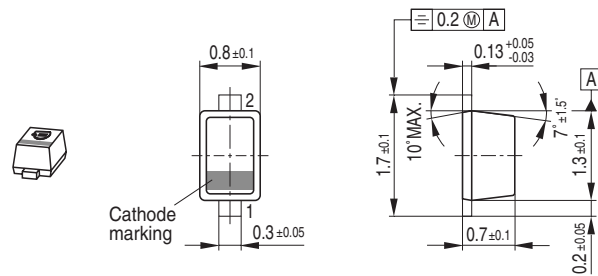
Code E6433: Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



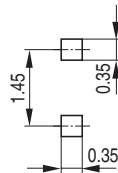
Data Code marking for discrete packages with
one digit (SCD80, SC79) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

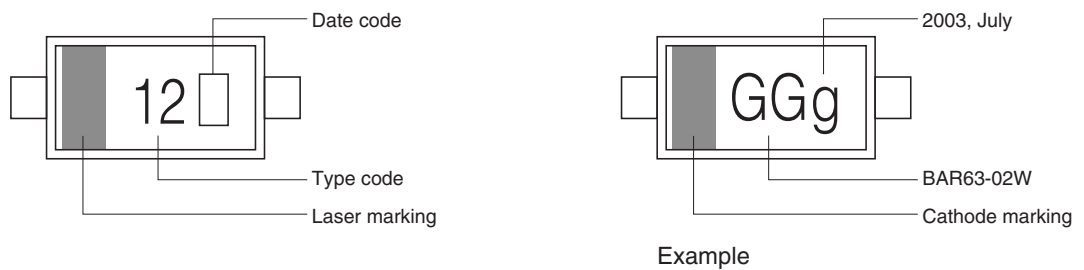
Package Outline



Foot Print

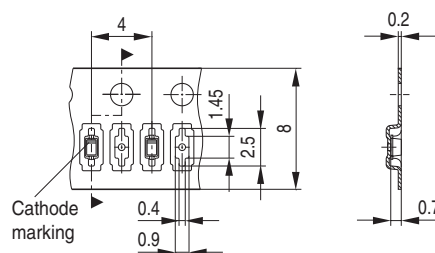


Marking Layout



Packing

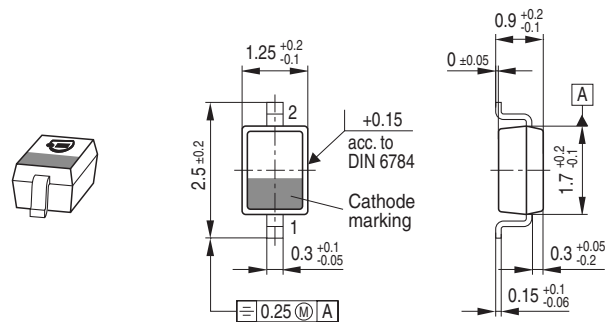
Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
Code E6433: Reel ø330 mm = 10.000 Pieces/Reel



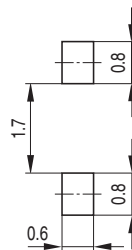
Data Code marking for discrete packages with one digit (SCD80, SC79) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

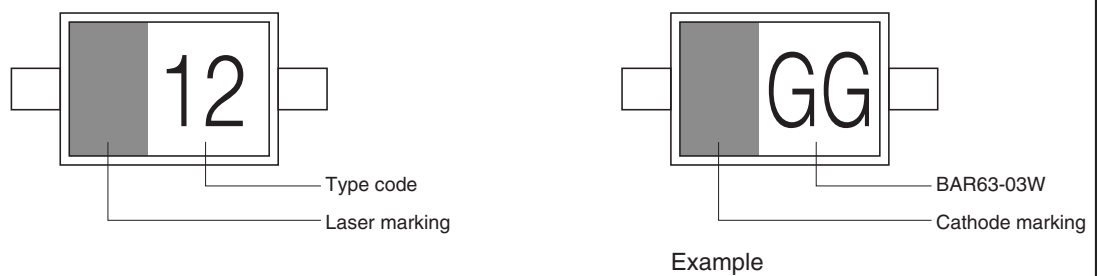
Package Outline



Foot Print

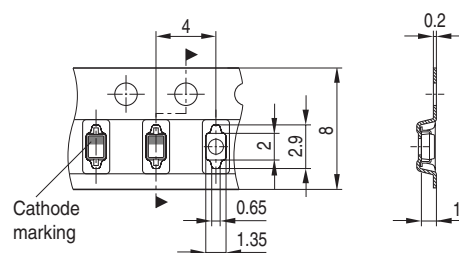


Marking Layout

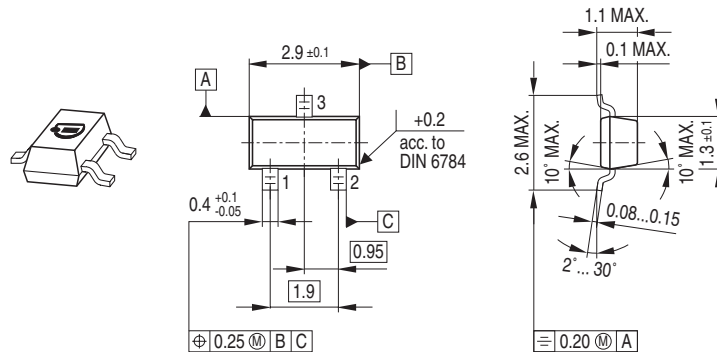


Packing

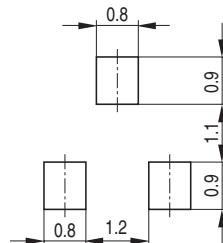
Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
 Code E6433: Reel ø30 mm = 10.000 Pieces/Reel



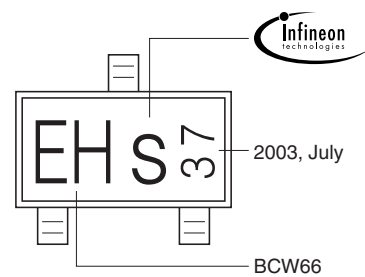
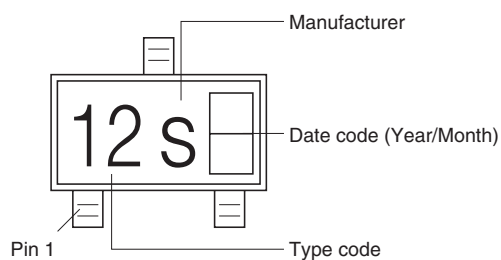
Package Outline



Foot Print



Marking Layout

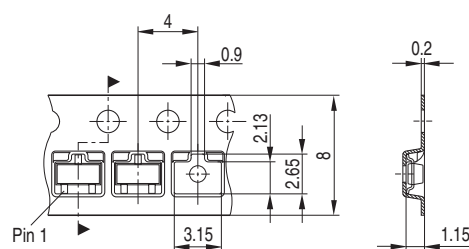


Example

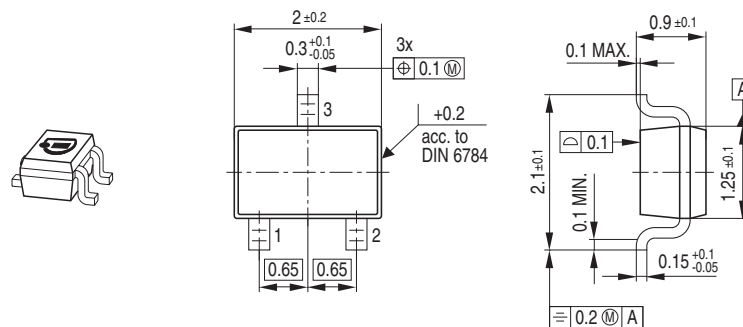
Packing

Code E6327: Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel

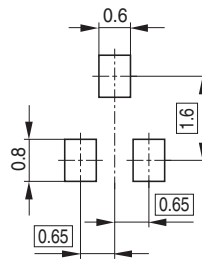
Code E6433: Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel



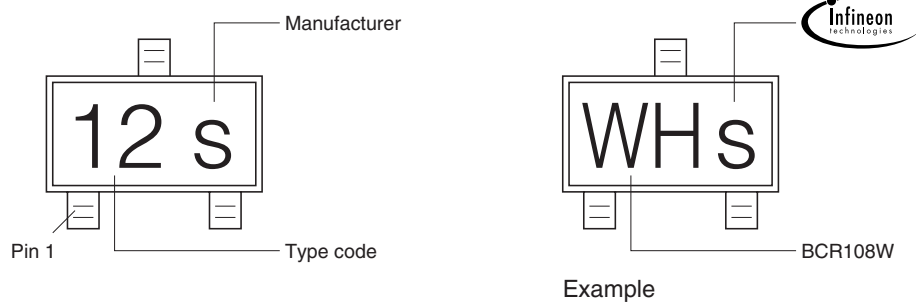
Package Outline



Foot Print

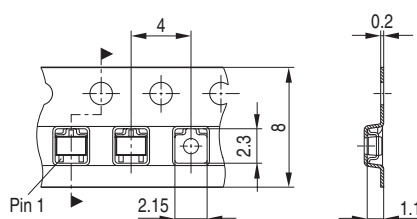


Marking Layout

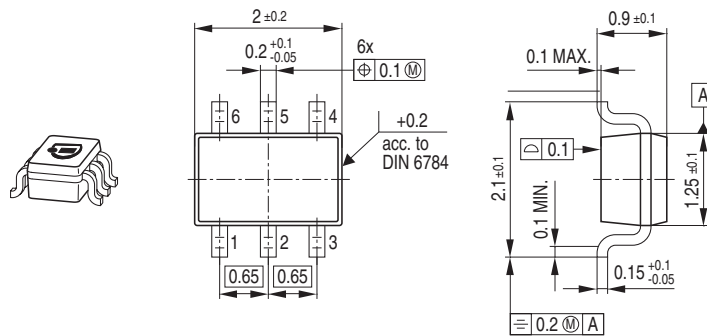


Packing

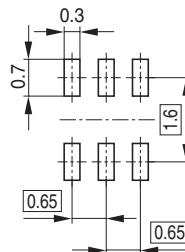
Code E6327: Reel ø180 mm = 3.000 Pieces/Reel
 Code E6433: Reel ø30 mm = 10.000 Pieces/Reel



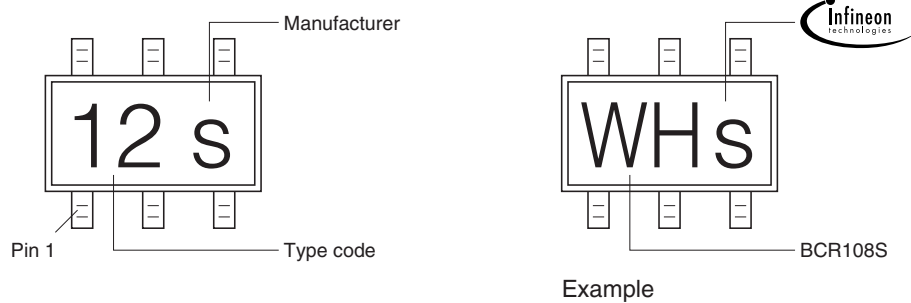
Package Outline



Foot Print

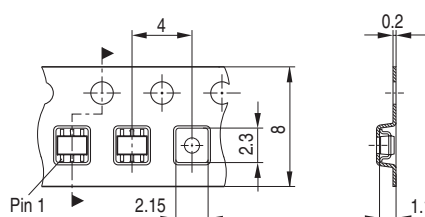


Marking Layout

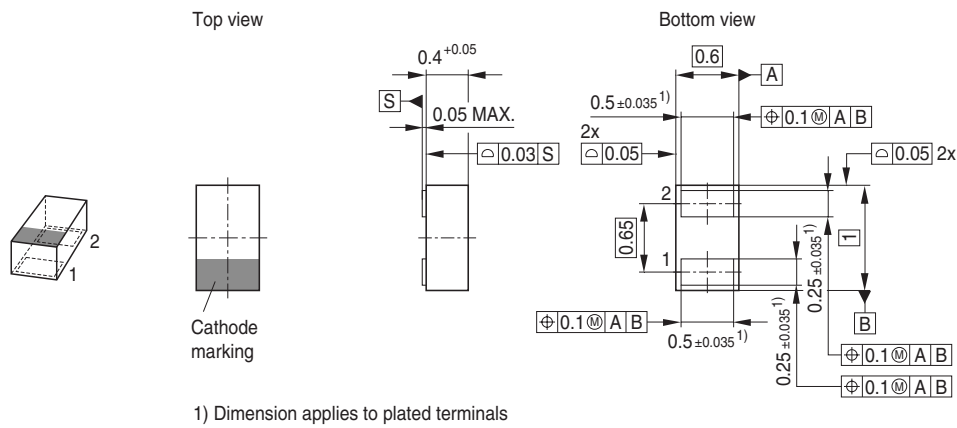


Packing

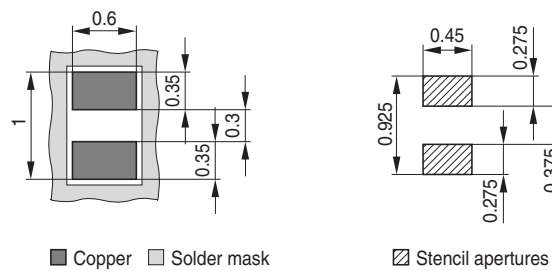
Code E6327: Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Code E6433: Reel $\varnothing 30$ mm = 10.000 Pieces/Reel



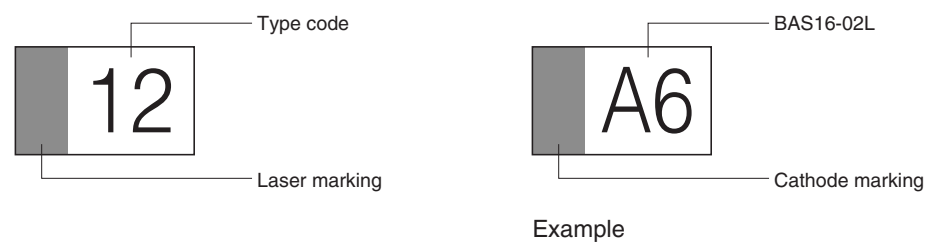
Package Outline



Foot Print

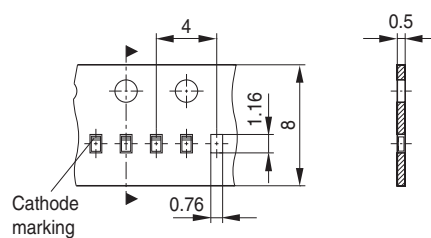


Marking Layout

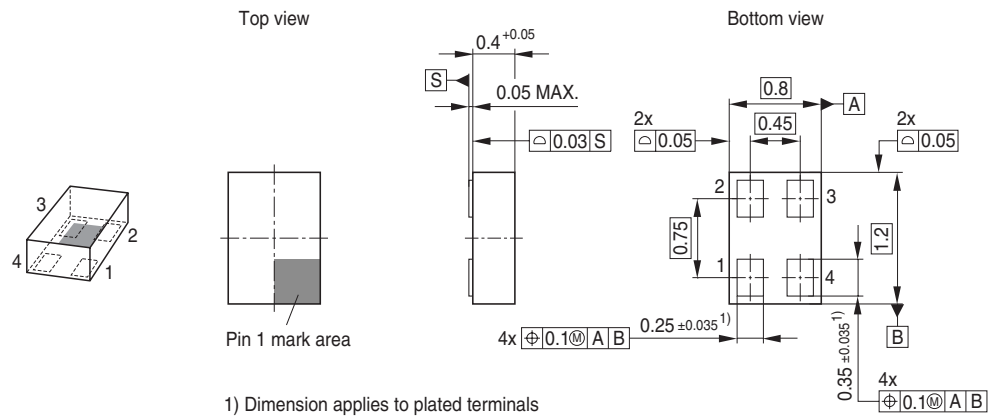


Packing

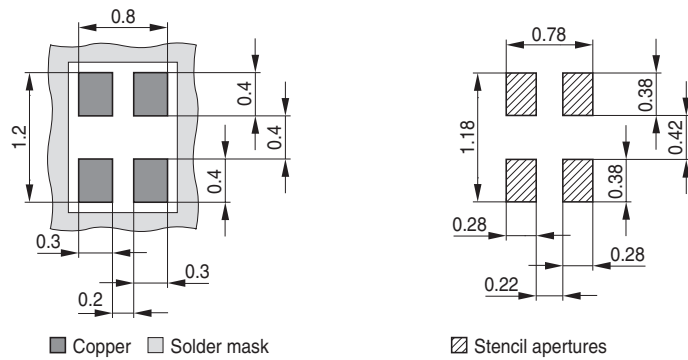
Code E6327: Reel $\varnothing$ 80 mm = 15.000 Pieces/Reel



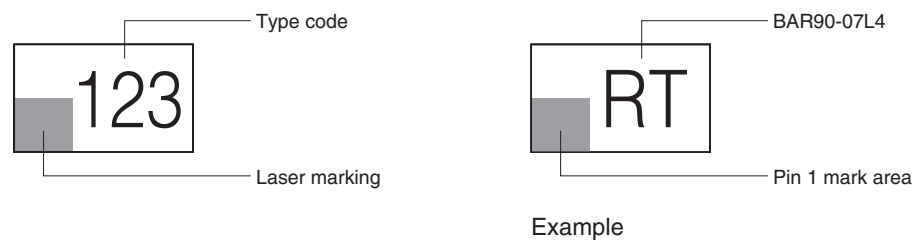
Package Outline



Foot Print

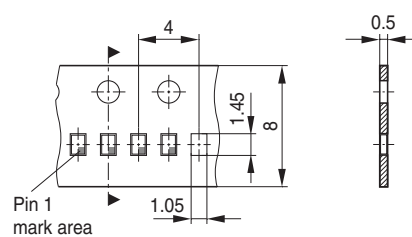


Marking Layout



Packing

Code E6327: Reel ø180 mm = 15.000 Pieces/Reel



Published by Infineon Technologies AG,
St.-Martin-Strasse 53,
81669 München
© Infineon Technologies AG 2005.
All Rights Reserved.

Attention please!

The information herein is given to describe certain components and shall not be considered as a guarantee of characteristics.

Terms of delivery and rights to technical change reserved.

We hereby disclaim any and all warranties, including but not limited to warranties of non-infringement, regarding circuits, descriptions and charts stated herein.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (www.infineon.com).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.

Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.